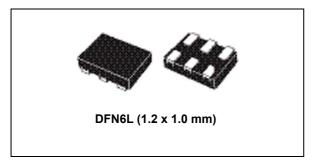


## Ear jack detection IC

Datasheet - preliminary data



### **Applications**

- Mobile phones
- Smart phones
- Tablet PCs
- Ultrabooks

#### **Features**

- Wide operating voltage range:
   V<sub>CC</sub> = 1.6 to 5.0 V single supply
- Low current consumption:  $I_{CC} = 6 \mu A \text{ max}$ .
- Integrated comparators, logic OR gate and N-channel MOSFET
- MIC to GND  $R_{DSON} = 0.8 \Omega$  typ.
- ESD 2 kV HBM
- Available in DFN6L (1.2 x 1.0 mm) package
- Operating temperature: -40 to 85 °C

Description STM3301

## 1 Description

The STM3301 device is an ear jack detection IC, which integrates a comparator with internal voltage reference, OR gate, pull up resistors for inputs and N-channel MOSFET with low  $R_{DSON}$  to avoid an unpleasant pop noise during jack insertion. The STM3301 device operates from  $V_{CC} = 1.6$  to 5.0 V and it is available in a DFN6L (1.2 x 1.0 mm) package making it ideal for portable applications.

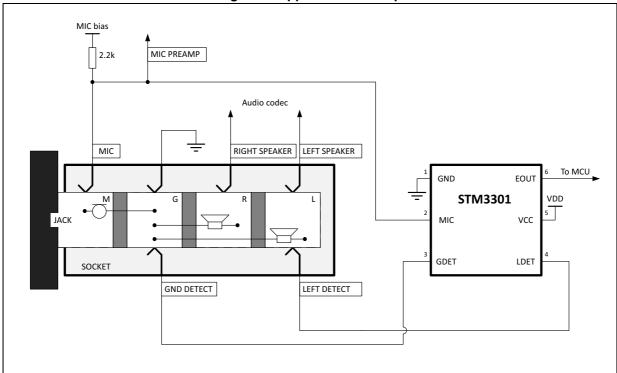


Figure 1. Application hookup

STM3301 **Description** 

VCC  $R_{\text{PU}}$ 270 KΩ $1 \, \text{M}\Omega$  . LDET EOUT  $V_{\text{R}}$  $R_{\text{PU}}$ 1 ΜΩ MIC  $1\,\mathrm{M}\Omega$  . **NMOS** GDET  $R_{DSON}$  = 0.8  $\Omega$ **GND** AM03358

Figure 2. Block diagram

Table 1. Truth table

| LDET | GDET | EOUT | MIC state |
|------|------|------|-----------|
| 0    | 0    | 0    | Hi-Z      |
| 0    | 1    | 1    | Low       |
| 1    | 0    | 1    | Low       |
| 1    | 1    | 1    | Low       |

Pin description STM3301

# 2 Pin description

Figure 3. Pinout

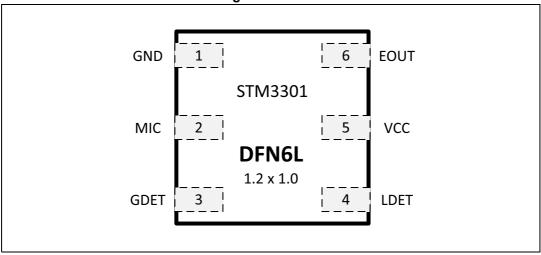


Table 2. Pin assignment

| Symbol | Pin | Туре     | Default state | Description  |
|--------|-----|----------|---------------|--|
| GND    | 1   | Power    | N/A           | System ground  |
| MIC    | 2   | I/O (OD) | Low           | Open drain active low I/O for MIC connection, see <i>Table 1</i> . |
| GDET   | 3   | I        | Open          | Ground jack socket connection                                      |
| LDET   | 4   | I        | Open          | Left speaker jack socket connection                                |
| VCC    | 5   | Power    | N/A           | Power supply   |
| EOUT   | 6   | O (PP)   | Low           | Jack insertion state output (push-pull); see <i>Table 1</i> .      |

STM3301 Maximum ratings

## 3 Maximum ratings

Stressing the device above the ratings listed in *Table 3: Absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in *Section 4* of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 3. Absolute maximum ratings

| Symbol                          | Parameter                              | Value       | Unit |
|---------------------------------|--|-------------|------|
| V <sub>CC</sub>                 | Power supply voltage                   | -0.3 to 6.0 | V    |
| V <sub>IN</sub>                 | DC input voltage                       | -0.3 to 6.0 | V    |
| I <sub>IK</sub>                 | Input clamp diode current              | -20         | mA   |
| V <sub>ESD</sub>                | HBM (JESD22-A114-A)                    | 2           | kV   |
| T <sub>STG</sub>                | Storage temperature range              | -65 to 150  | °C   |
| T <sub>SLD</sub> <sup>(1)</sup> | Lead solder temperature for 10 seconds | 260         | °C   |
| TJ                              | Junction temperature                   | 150         | °C   |

<sup>1.</sup> Reflow at peak temperature of 255 °C to 260 °C for less than 30 seconds (total thermal budget not to exceed 180 °C).

### 4 DC and AC parameters

This section summarizes the operating measurement conditions, and the DC and AC characteristics of the device. The parameters in *Table 4* to *Table 9* are derived from tests performed under the measurement conditions summarized in *Table 4* to *Table 9*. Designers should check that the operating conditions in their circuit match the operating conditions when relying on the quoted parameters.

Table 4. Recommended operation conditions

| Symbol          | Parameter                |     | Тур. | Max.            | Unit |
|-----------------|--------------------------|-----|------|-----------------|------|
| $V_{CC}$        | Supply voltage           | 1.6 |      | 5.0             | V    |
| V <sub>IN</sub> | DC input voltage         |     |      | V <sub>CC</sub> | V    |
| T <sub>A</sub>  | Operating temperature    |     |      | 85              | °C   |
| dt/dV           | Input rise and fall time |     |      | 10              | ns/V |

The test conditions are valid for ambient operating temperature  $T_A$  = -40 to +85 °C,  $V_{CC}$  = 1.8 V, all typical values are at 25 °C, the min. and max. values are over operating free air temperature range of -40 to 85 °C unless otherwise noted.

Table 5. General characteristics

| Symbol          | Parameter           | Test conditions                  | Min. | Тур. | Max. | Unit |
|-----------------|---------------------|----------------------------------|------|------|------|------|
| I <sub>CC</sub> | Current consumption | No jack: GDET, LDET are floating |      | 2.2  | 6    | μА   |

Table 6. LDET input characteristics

| Symbol                              | Parameter                 | Test conditions   | Min. | Тур. | Max. | Unit |
|-------------------------------------|---------------------------|---|------|------|------|------|
| $V_{IL}$                            | Low level input voltage   |   |      |      | 1.35 | V    |
| $V_{IH}$                            | High level input voltage  |   | 1.49 |      |      | ٧    |
| t <sub>PLH</sub> , t <sub>PHL</sub> | Propagation delay to EOUT | $R_L$ = 1 M $\Omega$ , $C_L$ = 15 pF<br>overdrive = 20 mV |      | 2.6  |      | μS   |
| I <sub>IH</sub>                     | High level input leakage  | $V_{I(LDET)} = V_{CC}$                                    |      | 0.1  |      | μА   |
| I <sub>IL</sub>                     | Low level input leakage   | V <sub>I(LDET)</sub> = 0 V                                |      | 1.8  |      | μА   |

Table 7. GDET input characteristics

| Symbol                              | Parameter                 | Test conditions                   | Min. | Тур. | Max. | Unit |
|-------------------------------------|---------------------------|-----------------------------------|------|------|------|------|
| $V_{IL}$                            | Low level input voltage   |                                   |      |      | 0.54 | V    |
| V <sub>IH</sub>                     | High level input voltage  |                                   | 1.17 |      |      | ٧    |
| t <sub>PLH</sub> , t <sub>PHL</sub> | Propagation delay to EOUT | $R_L = 1 M\Omega$ , $C_L = 15 pF$ |      | 0.4  |      | μS   |
| I <sub>IH</sub>                     | High level input leakage  | $V_{I(GDET)} = V_{CC}$            |      | 0.1  |      | μΑ   |
| I <sub>IL</sub>                     | Low level input leakage   | V <sub>I(GDET)</sub> = 0 V        |      | 1.8  |      | μΑ   |

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**Table 8. EOUT output characteristics** 

| Symbol          | Parameter                 | Test conditions                                   | Min. | Тур. | Max. | Unit |
|-----------------|---------------------------|---|------|------|------|------|
| V <sub>OL</sub> | Low level output voltage  | $I_{O(EOUT)} = -0.1 \text{ mA}$                   |      |      | 0.45 | V    |
| V <sub>OH</sub> | High level output voltage | $I_{O(EOUT)} = 0.1 \text{ mA}$                    | 1.35 |      |      | V    |
| t <sub>r</sub>  | Rise time                 | $R_L = 1 \text{ M}\Omega$ , $C_L = 15 \text{ pF}$ |      | 10   |      | ns   |
| t <sub>f</sub>  | Fall time                 | $R_L = 1 M\Omega$ , $C_L = 15 pF$                 |      | 10   |      | ns   |

### **Table 9. MIC output characteristics**

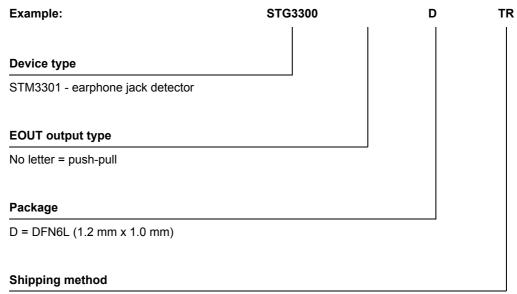
| Symbol            | Parameter                  | Test conditions              | Min. | Тур. | Max. | Unit |
|-------------------|----------------------------|------------------------------|------|------|------|------|
| R <sub>DSON</sub> | Shunt switch on resistance | I <sub>O(MIC)</sub> = 100 mA |      | 8.0  |      | Ω    |



Part numbering STM3301

# 5 Part numbering

Table 10. Ordering information scheme



TR = ECOPACK<sup>®</sup> package, tape and reel

STM3301 Package information

## 6 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: <a href="www.st.com">www.st.com</a>. ECOPACK is an ST trademark.

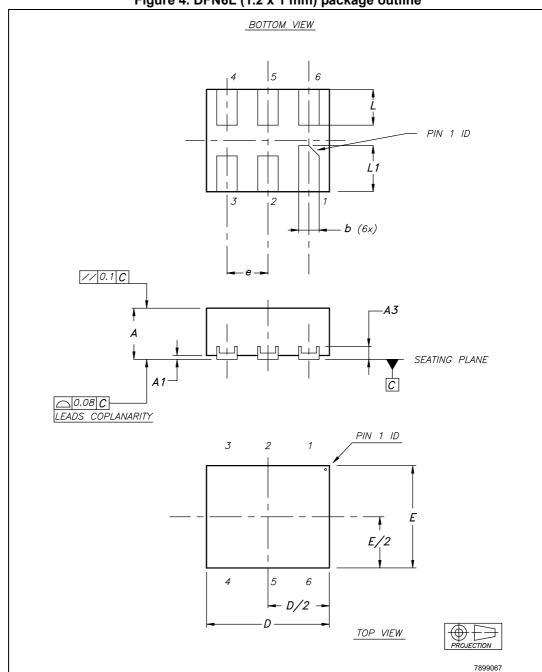


Figure 4. DFN6L (1.2 x 1 mm) package outline

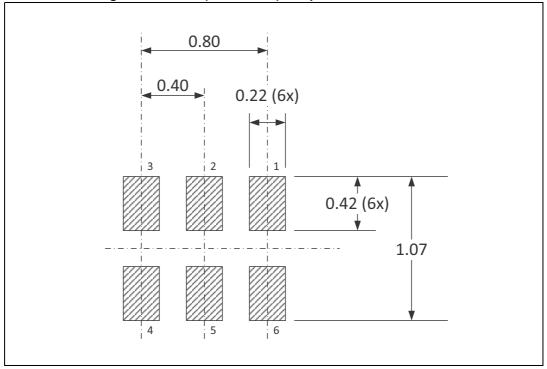
1. Drawing is not to scale.

Package information STM3301

Table 11. DFN6L (1.2 x 1 mm) package mechanical data

| Symbol | Dimensions (millimeters) |      |      |  |  |
|--------|--------------------------|------|------|--|--|
| Symbol | Тур.                     | Min. | Max. |  |  |
| Α      | 0.50                     | 0.45 | 0.55 |  |  |
| A1     | 0.02                     | 0    | 0.05 |  |  |
| A3     | 0.127                    |      |      |  |  |
| b      | 0.20                     | 0.15 | 0.25 |  |  |
| D      | 1.20                     | 1.15 | 1.25 |  |  |
| E      | 1                        | 0.95 | 1.05 |  |  |
| е      | 0.40                     |      |      |  |  |
| L      | 0.35                     | 0.30 | 0.40 |  |  |
| L1     | 0.45                     | 0.40 | 0.50 |  |  |

Figure 5. DFN6L (1.2 x 1 mm) footprint recommendation



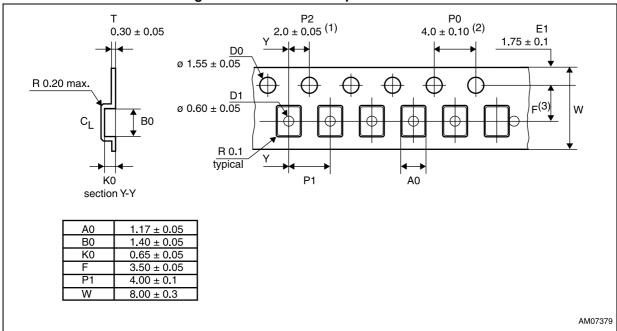


Figure 6. DFN6L carrier tape information

- 1. Measured from centerline of sprocket hole to centerline of pocket.
- 2. Cumulative tolerance of 10 sprocket holes is  $\pm$  0.20.
- 3. Measured from centerline of sprocket hole to centerline of pocket.
- 4. Other material available.
- 5. Drawing is not to scale.
- 6. All dimensions are in millimeters unless otherwise stated.

Package information STM3301

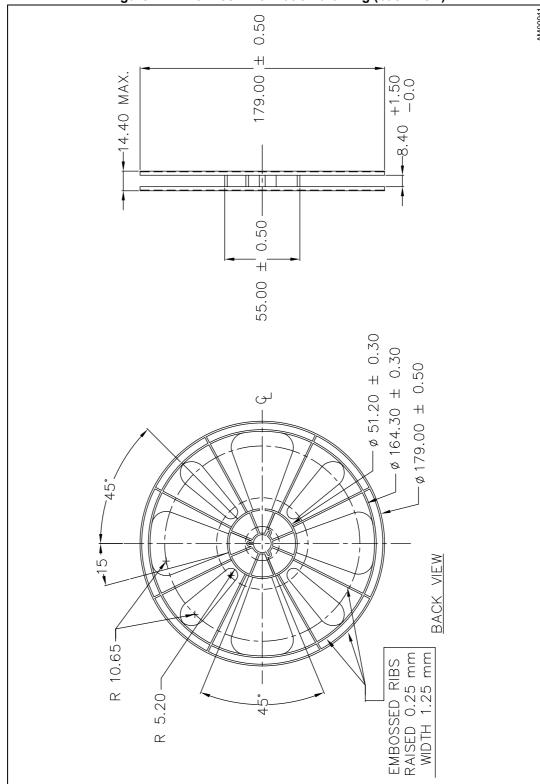


Figure 7. DFN6L reel information drawing (back view)

- 1. Drawing is not to scale.
- 2. Dimensions are in millimeters.

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STM3301 Package information

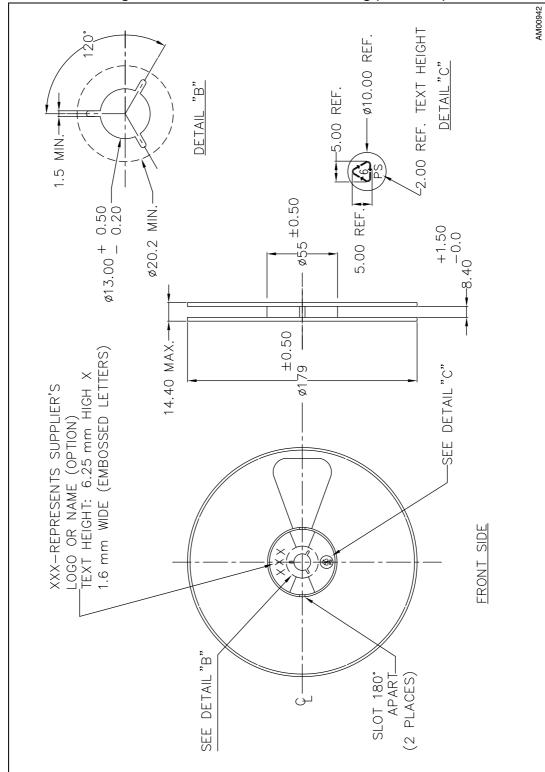


Figure 8. DFN6L reel information drawing (front view)

- 1. Drawing is not to scale.
- 2. Dimensions are in millimeters.

Revision history STM3301

# 7 Revision history

14/15

**Table 12. Document revision history** 

| Date        | Revision | Changes          |
|-------------|----------|------------------|
| 14-Oct-2013 | 1        | Initial release. |

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